

so that the second semiconductor chip on the first semiconductor chip is confined within an outer periphery of the first semiconductor chip; wherein

- Ans  
C*
- (a) the circuit board has a first pad, a second pad spaced away from the first pad in a direction along the outer periphery of the first semiconductor chip, and a wire connecting between the first pad and the second pad on a surface of the circuit board supporting the first semiconductor chip, the wire being printed on the circuit board together with the first pad and the second pad;
  - (b) the second semiconductor chip has a third pad positioned adjacent to the second pad but away from the first pad on the circuit board; and
  - (c) the second pad on the circuit board and the third pad on the second semiconductor chip are electrically connected through a bonding wire, so that the third pad on the second semiconductor chip is electrically connected with the first pad on the circuit board through the bonding wire, the second pad on the circuit board, and the wire on the circuit board.

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Please cancel claims 11 and 12.

**REMARKS**

This Amendment is being filed in response to the final Office Action dated September 25, 2003. For the following reasons this amendment should be entered, the application allowed, and the case passed to issue.

This amendment should be entered because no new matter or considerations are introduced, and this amendment clearly places the application in condition for allowance. Support for the amendment to claim 10 is found in claims 11, 12 and Fig. 1, 4, and 8, and the accompanying portions of the specification. No new considerations are raised because the